

Title (en)

PRODUCTION OF AN OPTOELECTRONIC COMPONENT THAT IS ENCAPSULATED IN PLASTIC, AND CORRESPONDING METHODS

Title (de)

HERSTELLEN EINES IN KUNSTSTOFF EINGEKAPSELTEN OPTOELEKTRONISCHEN BAUELEMENTES UND ZUGEHÖRIGE VERFAHREN

Title (fr)

PRODUCTION D'UN COMPOSANT OPTOELECTRONIQUE ENCAPSULE, DANS UNE MATIERE PLASTIQUE, ET PROCEDES CORRESPONDANTS

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Application

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Abstract (en)

[origin: WO2004105117A2] The invention relates to a simplified method for assembling optoelectronic components that are enclosed in plastic and the construction thereof. The individual component unit contains a semiconductor chip (11) and an optical window (10). A hermetic inclusion of at least the optically active areas of the semiconductor chip via the window ensues in the wafer-slicing process, i.e. before separation. A (window) wafer provided with recesses (7) and occupied, in areas, by a joining layer is joined to the pre-prepared semiconductor wafer (1) via the joining layer that seals the optically active areas. Before separation, the contact areas and the separating areas of the separation are exposed by a severing (8) that is precise with regard to the recesses. An inspection measuring of the component units can ensue when the wafers are joined.

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